**Preferred Device** 

## **Thyristor Surge Protectors**

## **High Voltage Bidirectional TSPD**

These Thyristor Surge Protective devices (TSPD) prevent overvoltage damage to sensitive circuits by lightning, induction and power line crossings. They are breakover–triggered crowbar protectors. Turn–off occurs when the surge current falls below the holding current value.

Secondary protection applications for electronic telecom equipment at customer premises.

- High Surge Current Capability: 50 Amps 10 x 1000 μsec Guaranteed at the extended temp range of –20°C to 65°C
- The MMT05B230T3 Series is used to help equipment meet various regulatory requirements including: Bellcore 1089, ITU K.20 & K.21, IEC 950, UL 1459 & 1950 and FCC Part 68.
- Bidirectional Protection in a Single Device
- Little Change of Voltage Limit with Transient Amplitude or Rate
- Freedom from Wearout Mechanisms Present in Non–Semiconductor Devices
- Fail—Safe, Shorts When Overstressed, Preventing Continued Unprotected Operation.
- Surface Mount Technology (SMT)
- **%** Indicates UL Registered File #E116110
- Device Marking: Logo, MMT05B230T3: RPBF; MMT05B260T3: RPBG; MMT05B310T3: RPBJ, and Date Code

### **MAXIMUM RATINGS** (T<sub>.J</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Off-State Voltage — Maximum MMT05B230T3 MMT05B260T3 MMT05B310T3	V <sub>DM</sub>	± 170 ± 200 ± 270	Volts
Maximum Pulse Surge Short Circuit Current Non-Repetitive Double Exponential Decay Waveform Notes 1, 2 10 x 1000 μsec (-20°C to +65°C) 8 x 20 μsec 10 x 160 μsec 10 x 560 μsec	IPPS1 IPPS2 IPPS3 IPPS4	±50 ±150 ±100 ±70	A(pk)
Maximum Non–Repetitive Rate of Change of On–State Current Double Exponential Waveform, R = 1.0, L = 1.5 $\mu$ H, C = 1.67 $\mu$ F, $I_{pk}$ = 110A	di/dt	±150	A/μs



http://onsemi.com

# 50 AMP SURGE 265 thru 365 VOLTS





SMB (No Polarity) (Essentially JEDEC DO-214AA) CASE 403C

#### **ORDERING INFORMATION**

Device	Package	Shipping
MMT05B230T3	SMB	12mm Tape and Reel (2.5K/Reel)
MMT05B260T3	SMB	12mm Tape and Reel (2.5K/Reel)
MMT05B310T3	SMB	12mm Tape and Reel (2.5K/Reel)

**Preferred** devices are recommended choices for future use and best overall value.

#### THERMAL CHARACTERISTICS

Characteristic		Max	Unit
Operating Temperature Range Blocking or Conducting State	T <sub>J1</sub>	-40 to +125	°C
Overload Junction Temperature — Maximum Conducting State Only	T <sub>J2</sub>	+175	°C
Instantaneous Peak Power Dissipation (I <sub>pk</sub> = 50A, 10x1000 μsec @ 25°C)		2000	W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Devices are bidirectional. All electrical parameters apply to forward and reverse polarities.

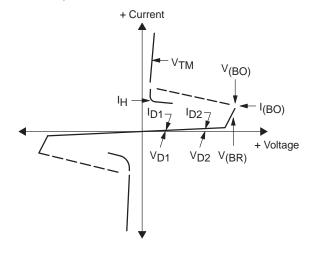
Characteristics		Symbol	Min	Тур	Max	Unit
Breakover Voltage (Both polarities) (dv/dt = 100 V/μs, I <sub>SC</sub> = 1.0 A, Vdc = 1000 V) (+65°C)	MMT05B230T3 MMT05B260T3 MMT05B310T3	V(BO)	_ _ _	_ _ _	265 320 365	Volts
(+00 0)	MMT05B230T3 MMT05B260T3 MMT05B310T3			_ _ _	280 340 400	
Breakover Voltage (Both polarities) (f = 60 Hz, ISC = 1.0 A(rms), VOC = 1000 V(rms), R <sub>I</sub> = 1.0 k $\Omega$ , t = 0.5 cycle, Note 2) (+65°C)	MMT05B230T3 MMT05B260T3 MMT05B310T3	V(BO)	_ _ _	_ _ _	265 320 365	Volts
(+03-0)	MMT05B230T3 MMT05B260T3 MMT05B310T3		_ _ _	_ _ _	280 340 400	
Breakover Voltage Temperature Coefficient		dV <sub>(BO)</sub> /dTJ	_	0.08	_	%/°C
Breakdown Voltage (I <sub>(BR)</sub> = 1.0 mA) Both polarities	MMT05B230T3 MMT05B260T3 MMT05B310T3	V <sub>(BR)</sub>	_ _ _	190 240 280	  	Volts
Off State Current ( $V_{D1} = 50 \text{ V}$ ) Both polarities ( $V_{D2} = V_{DM}$ ) Both polarities		I <sub>D1</sub> I <sub>D2</sub>		_	2.0 5.0	μА
On–State Voltage (I <sub>T</sub> = 1.0 A) (PW ≤ 300 μs, Duty Cycle ≤ 2%, Note 2)		VΤ	_	1.53	3.0	Volts
Breakover Current (f = 60 Hz, V <sub>DM</sub> = 1000 V(rms), R <sub>S</sub> Both polarities	$s = 1.0 \text{ k}\Omega$	I <sub>BO</sub>	_	230	_	mA
Holding Current (Both polarities) VS = 500 Volts; IT (Initiating Current) = ±1.0 Amp	Note 2 (+65°C)	lΗ	175 130	340 —	_	mA
Critical Rate of Rise of Off–State Voltage (Linear waveform, V <sub>D</sub> = Rated V <sub>BR</sub> , T <sub>J</sub> = 25°C)		dv/dt	2000	_	_	V/µs
Capacitance (f = 1.0 MHz, 50 Vdc, 1.0 V rms Signal) (f = 1.0 MHz, 2.0 Vdc, 15 mV rms Signal)		СО	_	22 53	— 75	pF

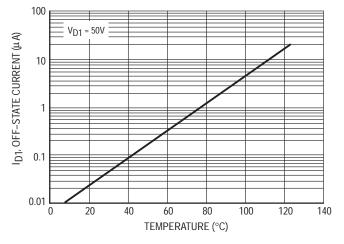
<sup>(1)</sup> Allow cooling before testing second polarity.

<sup>(2)</sup> Measured under pulse conditions to reduce heating.

# Voltage Current Characteristic of TSPD (Bidirectional Device)

Symbol	Parameter
I <sub>D1</sub> , I <sub>D2</sub>	Off State Leakage Current
V <sub>D1</sub> , V <sub>D2</sub>	Off State Blocking Voltage
V <sub>BR</sub>	Breakdown Voltage
V <sub>BO</sub>	Breakover Voltage
IBO	Breakover Current
lΗ	Holding Current
V <sub>TM</sub>	On State Voltage





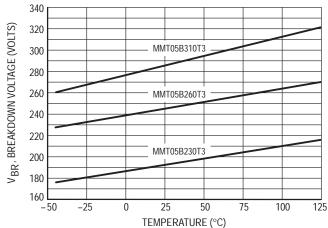


Figure 1. Off-State Current versus Temperature

Figure 2. Breakdown Voltage versus Temperature

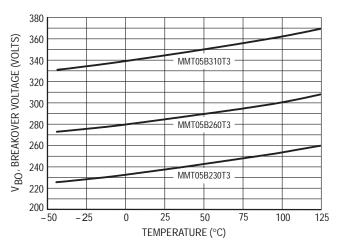


Figure 3. Breakover Voltage versus Temperature

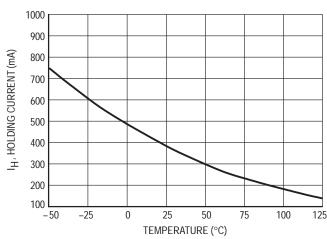


Figure 4. Holding Current versus Temperature

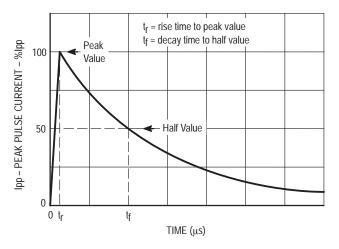


Figure 5. Exponential Decay Pulse Waveform

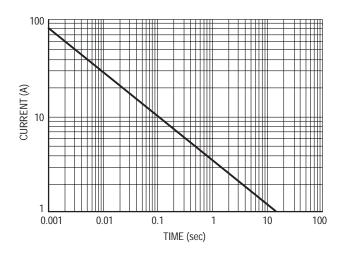
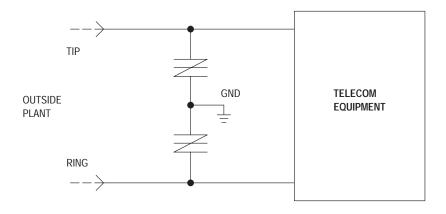
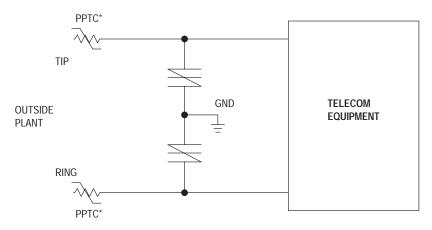
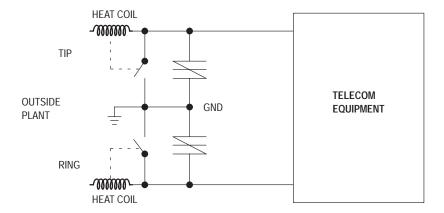


Figure 6. Peak Surge On–State Current versus Surge Current Duration, Sinusoidal Waveform





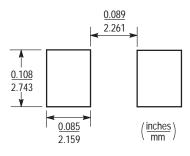
\*Polymeric PTC (positive temperature coefficient) overcurrent protection device



## MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection

interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.

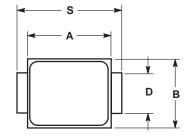


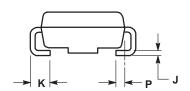
**SMB** 

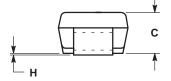
### **PACKAGE DIMENSIONS**

#### **SMB**

(No Polarity) (Essentially JEDEC DO-214AA) CASE 403C-01 **ISSUE O** 







- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	INCHES		MILLIN	LIMETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.160	0.180	4.06	4.57	
В	0.130	0.150	3.30	3.81	
С	0.075	0.095	1.90	2.41	
D	0.077	0.083	1.96	2.11	
Н	0.0020	0.0060	0.051	0.152	
J	0.006	0.012	0.15	0.30	
K	0.030	0.050	0.76	1.27	
Р	0.020 REF		F 0.51 REF		
S	0.205	0.220	5.21	5.59	



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